



Material Content Data Sheet



Sales Product Name		BTS4130QGA		Issued		29. August 2013		
MA#		MA001114808						
Package		PG-DSO-20-32		Weight*		478.31 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	7.009	1.47	1.47	14654	14654
leadframe	inorganic material	phosphorus	7723-14-0	0.036	0.01		75	
	non noble metal	zinc	7440-66-6	0.143	0.03		299	
	non noble metal	iron	7439-89-6	2.862	0.60		5983	
wire	non noble metal	copper	7440-50-8	116.197	24.29	24.93	242932	249289
	non noble metal	aluminium	7429-90-5	0.464	0.10	0.10	970	970
	encapsulation	organic material	carbon black	1333-86-4	0.692	0.14		1446
	plastics	epoxy resin	-	31.822	6.65		66529	
	inorganic material	silicondioxide	60676-86-0	313.373	65.53	72.32	655168	723143
leadfinish	non noble metal	tin	7440-31-5	2.746	0.57	0.57	5741	5741
plating	non noble metal	nickel	7440-02-0	0.341	0.07		713	
	inorganic material	phosphorus	7723-14-0	0.001	0.00		2	
glue	non noble metal	silver	7440-22-4	0.588	0.12	0.19	1230	1945
	plastics	epoxy resin	-	0.356	0.07		745	
	noble metal	silver	7440-22-4	1.680	0.35	0.42	3513	4258
*deviation	< 10%				Sum in total:		100.00	1000000

Important Remarks:

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